

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KONICA MINOLTA, INC.	07/23/2015
RECEIVING PARTY DATA	
Name:	WAKO PURE CHEMICAL INDUSTRIES, LTD.
Street Address:	1-2, DOSHOMACHI 3-CHOME
Internal Address:	CHUO-KU, OSAKA-SHI
City:	OSAKA
State/Country:	JAPAN
Postal Code:	540-8605
Name:	KONICA MINOLTA, INC.
Street Address:	2-7-2 MARUNOUCHI
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-7015
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13882352
CORRESPONDENCE DATA	
Fax Number:	(312)321-4299
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	12062-231
NAME OF SUBMITTER:	JOHN C. FREEMAN

SIGNATURE:	/John C. Freeman/
DATE SIGNED:	08/27/2015
Total Attachments: 3 source=12062-231_Asst#page1.tif source=12062-231_Asst#page2.tif source=12062-231_Asst#page3.tif	

ASSIGNMENT

WHEREAS, Konica Minolta, Inc., a corporation organized and existing under the laws of Japan and having a place of business at 2-7-2 Marunouchi, Chiyoda-ku, Tokyo 100-7015 Japan, hereinafter called the "Assignor", currently possesses the entire right, title and interest in and to the inventions described in 1) the United States patent application entitled MICROCHIP, MOLDING DIE FOR MICROCHIP, AND MANUFACTURING APPARATUS FOR MANUFACTURING MICROCHIP, for a full description of which reference is here made to an application for Letters Patent of the United States filed on April 29, 2013 and assigned Application Serial No. 13/882,352; and 2) the Patent Cooperation Treaty patent application entitled MICROCHIP, MICROCHIP SHAPING DIE, AND MANUFACTURING APPARATUS FOR MANUFACTURING MICROCHIP, for a full description of which reference is here made to Patent Cooperation Treaty Patent Application No. PCT/JP2011/074478 filed on October 25, 2011;

WHEREAS, Wako Pure Chemical Industries, Ltd., a corporation organized and existing under the laws of Japan, having a place of business at 1-2, Doshomachi 3-chome, Chuo-ku, Osaka-shi, Osaka 540-8605 Japan, hereinafter called the "Assignee", desires to acquire a 50% share in the rights, title and interest in and to the inventions and the patent applications identified above, and all patents which may be obtained for said inventions, as set forth below;

NOW, THEREFORE, in exchange for valuable and legally sufficient consideration, the receipt of which by the Assignor from the Assignee is hereby acknowledged, the Assignor has sold, assigned and transferred, and by these presents does sell, assign and transfer to the Assignee, a 50% share in the Assignor's rights, title and interest for the United States, its territories and possessions, in and to the inventions and the patent applications identified above, and any patents that may issue for said inventions in the United States, including a 50% share of Assignor's right to claim for any such applications all benefits and priority rights under any applicable convention; together with a 50% share of Assignor's right, title and interest in and to all

continuations, continuations-in-part, divisions, renewals and extensions or reissues of any of the patent applications and patents defined above; together with the right to recover 50% of damages, including, but not limited to, a reasonable royalty, by reason of present, or future infringement or any other present or future violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents. The Assignor hereby sells, assigns, and transfers a 50% share of Assignor's rights, title and interest to the Assignee as of the day of execution of the present Assignment.

The Assignee hereby covenants and agrees, for both the Assignee and the Assignee's legal representatives, that the Assignee will assist the Assignor in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignor may elect to make covering the inventions identified above; and that the Assignee will execute and deliver to the Assignor any and all additional papers which may be requested by the Assignor to carry out the terms of this Assignment;

The Assignor hereby covenants and agrees, for both the Assignor and the Assignor's legal representatives, in vesting in the Assignee like 50% share of Assignor's title in and to all such other patent applications and patents.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignor and the Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignor and Assignee have executed this agreement.

Signed for and on behalf of
Konica Minolta, Inc.

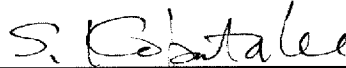
This 23 day of July, 2015



Kenichi Sanada
Executive Officer

Signed for and on behalf of
Wako Pure Chemical Industries, Ltd.

This 4th day of August, 2015



Shinzo Kobatake
President and CEO